

Institute of Electrical and Electronics Engineers, Inc.

Phoenix Section

**Components, Packaging and Manufacturing Technology Society Chapter
& Waves and Devices Chapter**

PRESENT AN ALL-DAY WORKSHOP ON

Emerging Device and Packaging Technologies

Date: Tuesday, December 11th, 2007

Time: 7:00 A.M. – 5:00 P.M.

Location: Arizona State University, Tempe, Arizona – ASU Memorial Union (Arizona Room)

The semiconductor industry is entering an era with tremendous opportunities to exploit emerging technologies for the benefit of widely diverse markets. Moore's Law requires increasingly intensive materials innovations to maintain its momentum. Meanwhile, new markets in the areas of bio-electronics, sensors, etc., are leveraging the existing manufacturing infrastructure while incorporating new materials and techniques. This one-day workshop will bring together experts from industry, academia, research labs, and consortia to share their technology roadmaps and visions, novel materials and methods, and discuss technical opportunities. The status and challenges facing device, interconnect, and packaging technologies will be discussed in depth. Vendors will be on hand to exhibit products and services in all aspects of the supply chain for IC, packaging, and module design and manufacturing.

Topics

- Nanotechnology and Continuum Model Limits
- ITRS Roadmap Challenges
- SiP: 3D, Modules, Discrete Passives Integration
- Flexible Electronics
- Green Materials and Packaging
- Bioelectronics and Sensors Technologies
- General Industry and Technology Visions
- Panel Discussion on Future Challenges and Opportunities for Emerging Technologies

For General Information: www.ieee.org/phoenix

For Registration Forms: Sergio Pacheco (480) 413-3737

For Vendor Forms: Vladimir Noveski (480) 554-2375

CALL FOR PAPERS – Semi-Therm 24

Abstracts for **Semi-Therm 24** are due on **October 20, 2007**. We are expecting an exciting list of sessions this year with several special sessions planned, so get your abstract in on time. We will be notifying accepted authors by December 1, 2007, and full manuscripts are due January 12, 2008.

Semi-Therm is soliciting papers on current thermal management technologies, practical application issues, modeling and measurement of electronic components and systems, including the following areas:

- Packaging Level
- Materials
- Modeling and Analysis
- Cooling Technologies
- Applications

The abstract should be between two and five pages of single-spaced text giving the key results, findings and conclusions, and should be supported by additional pages of figures tables and references as appropriate. Abstracts must demonstrate that proposed papers are appropriate for Semi-Therm and of high technical quality.

ABSTRACT DEADLINE October 20

**Semiconductor Thermal Measurement
and Management Symposium
March 16-20, 2008,
San Jose, California USA**

See full Call for Papers, other information on our website:

www.semi-therm.org

For further information, please contact the program chair via e-mail:

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